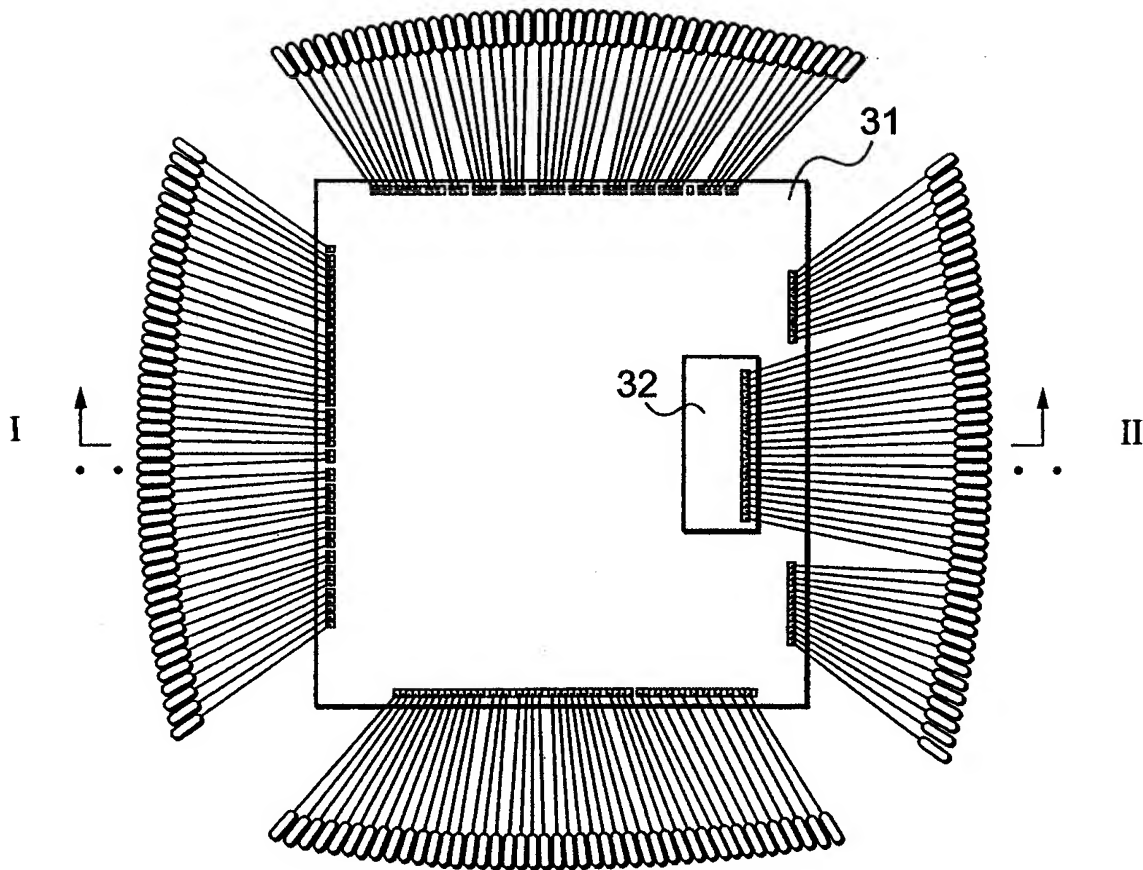


FIG. 1



2/5

FIG. 2

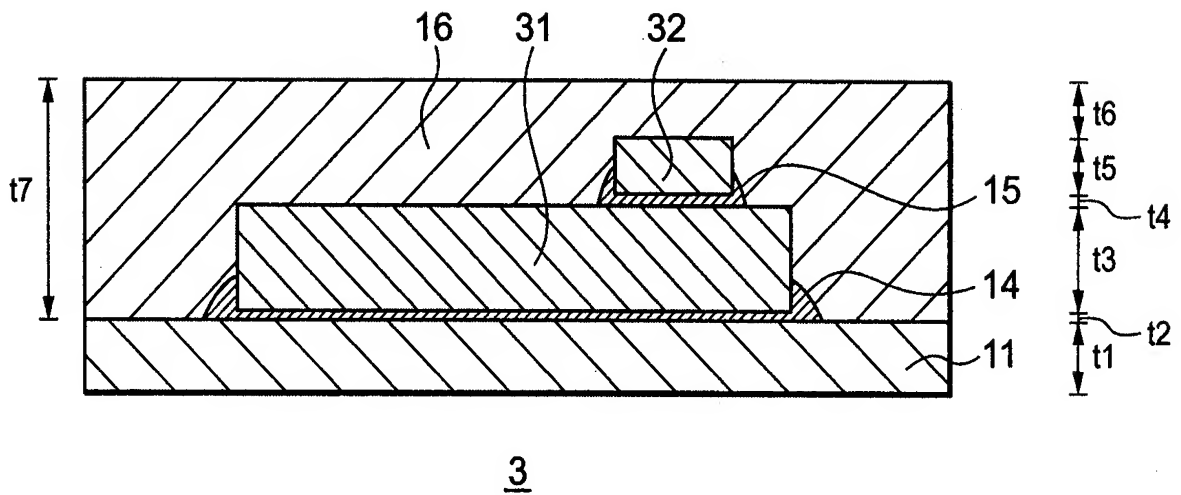


FIG. 3

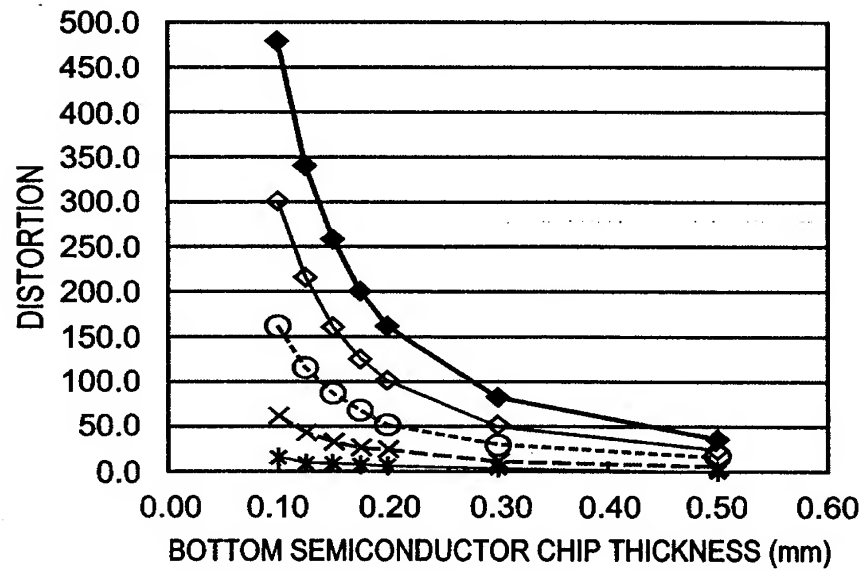


FIG. 4

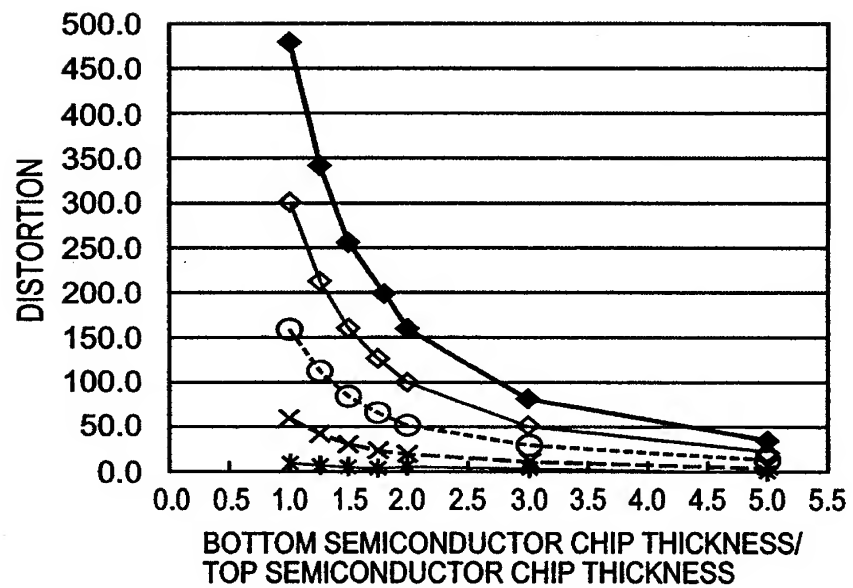


Figure 4 is a perspective view of a curved, elongated component 4. The component has a main body 11 with a series of parallel diagonal lines. A smaller, rectangular component 41 is mounted on top of the main body. A label 12 points to a specific feature on the main body.

Figure 1 is a cross-sectional view of a semiconductor device. The device includes a substrate 11, a first conductive layer 12, a second conductive layer 13, a gate stack 14, a gate electrode 15, and a gate insulating layer 16. The gate stack 14 is formed on the substrate 11, and the gate electrode 15 is formed on the gate stack 14. The gate insulating layer 16 is formed on the gate electrode 15.

5/5

FIG. 8

PRIOR ART

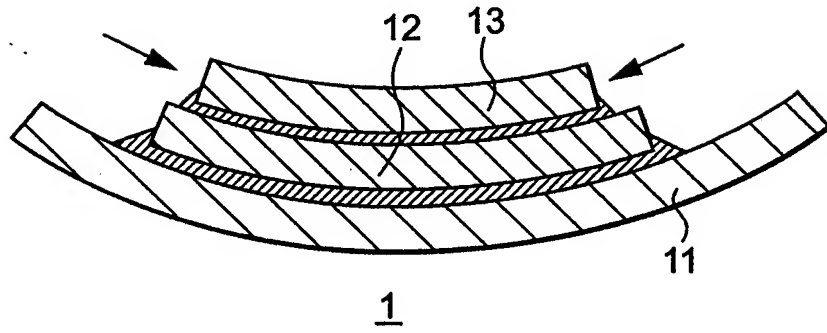


FIG. 9

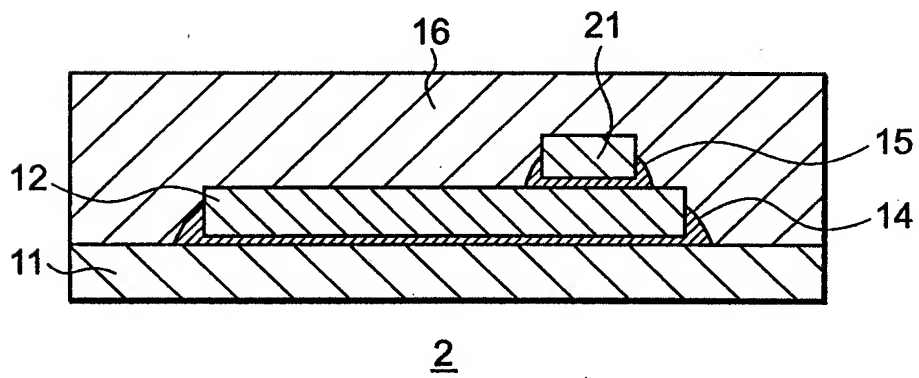


FIG. 10

